

Notice of References Cited	Application/Control No. 10/733,431	Applicant(s)/Patent Under Reexamination BERNE ET AL.	
	Examiner Evan Pert	Art Unit 2826	Page 1 of 1

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	V	Q.Y. Tong et al., "Low Temperature Si Layer Splitting," October 1997, Proceedings of the 1997 IEEE International SOI Conference, pages 126-127.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.